2026 Taiwan ESD and Reliability Conference

Dates: Nov. 4-6, 2026
Location: National Yang Ming Chiao Tung University, Hsinchu, Taiwan
Organizer: Taiwan ESD Association (T-ESDA)
Co-organizer: National Yang Ming Chiao Tung University
and Taiwan Reliability Technology Association (TRTA)
Conference Website: https://alab.iee.nycu.edu.tw/~esd/TESDC/

ORGANIZING COMMITTEE

Conference Advisor

Ming-Dou Ker, *National Yang Ming Chiao Tung University*

General Chair

Shao-Chang Huang, *Solomon Systech Limited*

TPC Chair

Cher Ming Tan, *Chang Gung University*

Technical Program Committee

(Invitations in Progress)

Organizer

Taiwan ESD Association
President－Chun-Yu Lin
Secretary General－Dunken Lee
Executive Secretary－Lyn Liu
E-Mail: taiwanesda@gmail.com

Call for Papers

Enhancing the research and development capabilities in ESD protection and Reliability technologies has become a critical focus within the electronics industry. The Taiwan ESD Association (T-ESDA) is dedicated to promoting technical exchange in these fields and cordially invites professionals from academia, industry, and research institutions to contribute papers and share practical experiences and research findings related to ESD and Reliability.

The annual symposium not only showcases cutting-edge research from the experts but also serves as a platform for in-depth technical discussions, allowing participants to explore effective solutions to real-world challenges. Through this event, T-ESDA aims to strengthen collaboration among academia, industry, and research communities, and to advance the development of ESD protection and Reliability technologies in response to the evolving needs of the electronics sector.

This conference focuses on the ESD protection and reliability related technologies. Papers related to the studies on analysis and solutions for practical cases are specifically interested. **Topics of interest include, but are not limited to:**

※ Component Level ESD Issue
※ System-Level ESD/EMI Issue
※ Factory-Level ESD Issue
※ EDA Verification
※ ESD Materials Technology
※ ESD Testing － Components, System, Factory & Materials
※ Failure Analysis
※ Recent Patents on ESD and Reliability
※ System Reliability Analysis and Lifetime Prediction
※ Component Reliability Analysis and Lifetime Prediction
※ Accelerated Stress Testing and Lifetime Extrapolation
※ Reliability Failure Physics and Failure Mechanisms
※ Failure Analysis Methodologies
※ Maintainability
※ Reliability Requirements Setting and Planning
※ Reliability Screening

Information for Authors

1. Papers should be accomplished in A4 paper size. It should be in a camera-ready format. The submission shall be made electronically (in PDF format).
2. Paper Submission Deadline: Aug. 15, 2026
3. Paper Acceptance Announcement: Sep. 30, 2026
4. About the paper format and the most updated news release, please visit https://alab.iee.nycu.edu.tw/~esd/TESDC/